

Features

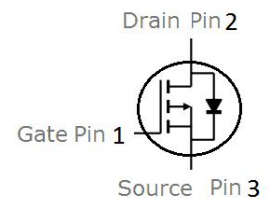
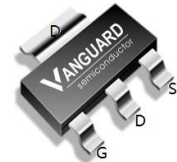
- P-Channel, -5V Logic Level Control
- Very low on-resistance $R_{DS(on)}$ @ $V_{GS} = -4.5V$
- Fast Switching
- Enhancement mode
- Pb-free lead plating; RoHS compliant


Halogen-Free

Part ID	Package Type	Marking	Tape and reel information
VSZ260P10MS	SOT223	260P10M	2500pcs/reel

V_{DS}	-100	V
$R_{DS(on),TYP} @ V_{GS} = -10V$	250	mΩ
$R_{DS(on),TYP} @ V_{GS} = -4.5V$	260	mΩ
I_D	-2.2	A

SOT223



Maximum ratings, at $T_j = 25^\circ\text{C}$, unless otherwise specified

Symbol	Parameter		Rating	Unit
Common Ratings				
V _{GS}	Gate-Source Voltage		±20	V
V _{(BR)DSS}	Drain-Source Breakdown Voltage		-100	V
T _{STG} T _J	Storage and operating temperature range①		-55 to 150	°C
I _S	Diode Continuous Forward Current	T _A =25°C	-2.2	A
Mounted on Large Heat Sink				
I _D	Continuous Drain current @V _{GS} =-10V	T _A =25°C	-2.2	A
		T _A =100°C	-1.4	A
I _{DM}	Pulse Drain Current Tested ②	T _A =25°C	-8	A
P _D	Maximum Power Dissipation	T _A =25°C	2.5	W
R _{θJL}	Thermal Resistance-Junction to Lead		35	°C/W
R _{θJA}	Thermal Resistance Junction-Ambient		50	°C/W
Drain-Source Avalanche Ratings				
EAS	Avalanche Energy, Single Pulsed ③		TBD	mJ



Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
Static Electrical Characteristics @ T _j = 25°C (unless otherwise stated)						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V I _D =-250μA	-100	--	--	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-100V,V _{GS} =0V	--	--	-1	μA
	Zero Gate Voltage Drain Current(T _j =125°C)	V _{DS} =-100V,V _{GS} =0V	--	--	-100	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±20V,V _{DS} =0V	--	--	±100	nA
V _{GS(TH)}	Gate Threshold Voltage	V _{DS} =V _{GS} ,I _D =-250μA	-1.0	-1.8	-2.5	V
R _{DS(ON)}	Drain-Source On-State Resistance ②	V _{GS} =-10V, I _D =-2A	--	250	265	mΩ
R _{DS(ON)}	Drain-Source On-State Resistance ②	V _{GS} =-4.5V, I _D =-1A	--	260	280	mΩ
Dynamic Electrical Characteristics @ T _j = 25°C (unless otherwise stated)						
C _{iss}	Input Capacitance	V _{DS} =-30V,V _{GS} =0V, f=1MHz	--	960	--	pF
C _{oss}	Output Capacitance		--	40	--	pF
C _{rss}	Reverse Transfer Capacitance		--	25	--	pF
R _g	Gate Resistance	f=1MHz	--	82	--	Ω
Q _g	Total Gate Charge	V _{DS} =-50V,I _D =-2A, V _{GS} =-10V	--	13	--	nC
Q _{gs}	Gate-Source Charge		--	2.8	--	nC
Q _{gd}	Gate-Drain Charge		--	4.5	--	nC
Switching Characteristics						
t _{d(on)}	Turn-on Delay Time	V _{DD} =-50V, I _D =-2A, R _G =6.8Ω, V _{GS} =-10V	--	10	--	nS
t _r	Turn-on Rise Time		--	21	--	nS
t _{d(off)}	Turn-Off Delay Time		--	45	--	nS
t _f	Turn-Off Fall Time		--	17	--	nS
Source- Drain Diode Characteristics@ T _j = 25°C (unless otherwise stated)						
V _{SD}	Forward on voltage	I _{SD} =-2A,V _{GS} =0V	--	-0.83	-1.2	V
t _{rr}	Reverse Recovery Time	T _j =25°C,I _{sd} =-2A, V _{GS} =0V	--	15	--	nS
Q _{rr}	Reverse Recovery Charge	di/dt=-100A/μs		48		nC

NOTE:

① Repetitive rating; pulse width limited by max. junction temperature.

② Pulse width ≤ 300μs; duty cycles ≤ 2%.

③ Limited by T_{Jmax}, starting T_J = 25°C, L = 0.5mH, R_G = 25Ω, I_{AS} = TBD, V_{GS} = -10V. Part not recommended for use above this value



Typical Characteristics

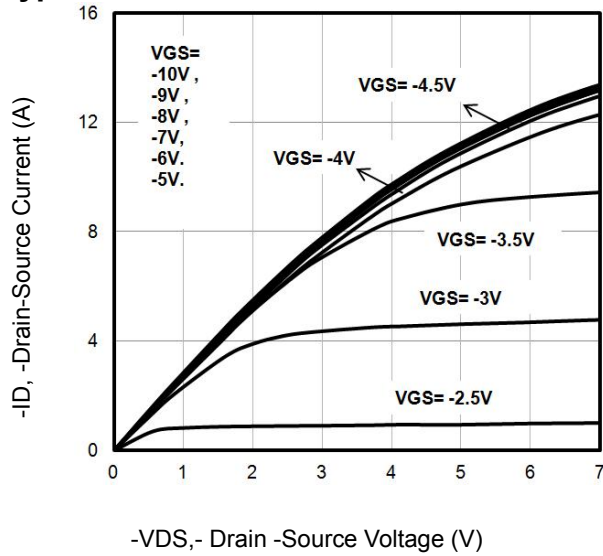


Fig1. Typical Output Characteristics

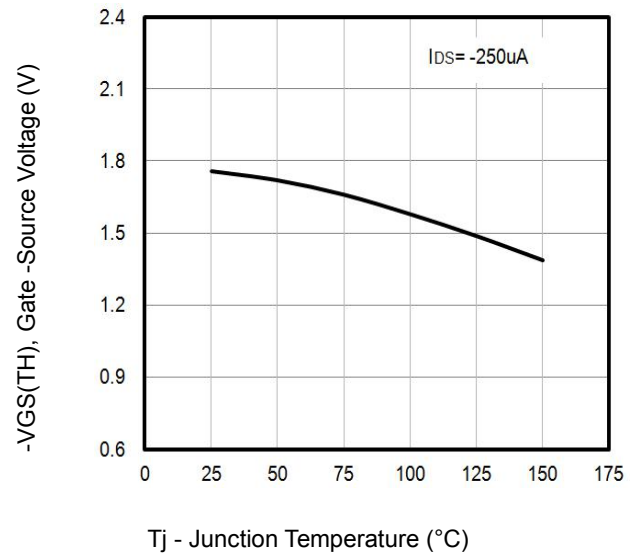


Fig2. $-V_{GS(TH)}$ Gate-Source Voltage Vs. T_j

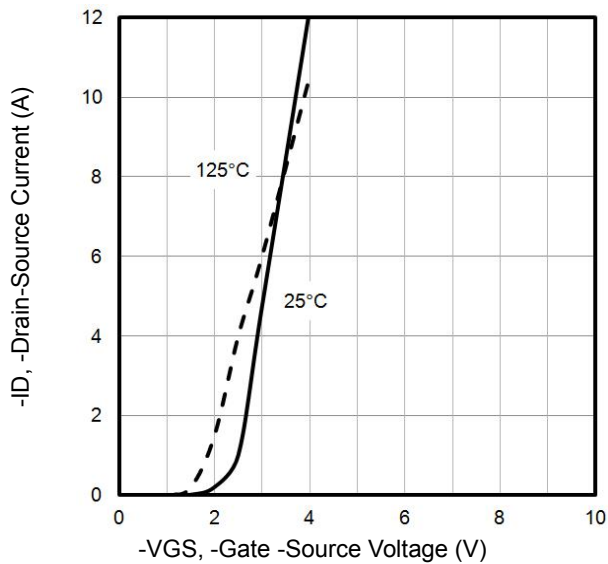


Fig3. Typical Transfer Characteristics

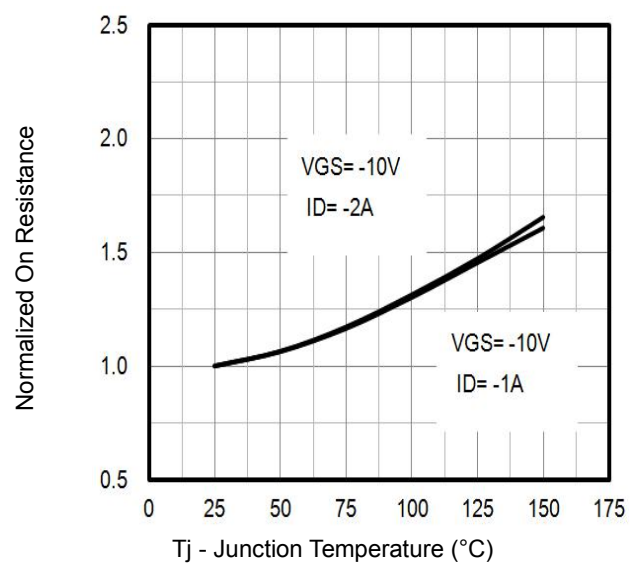


Fig4. Normalized On-Resistance Vs. T_j

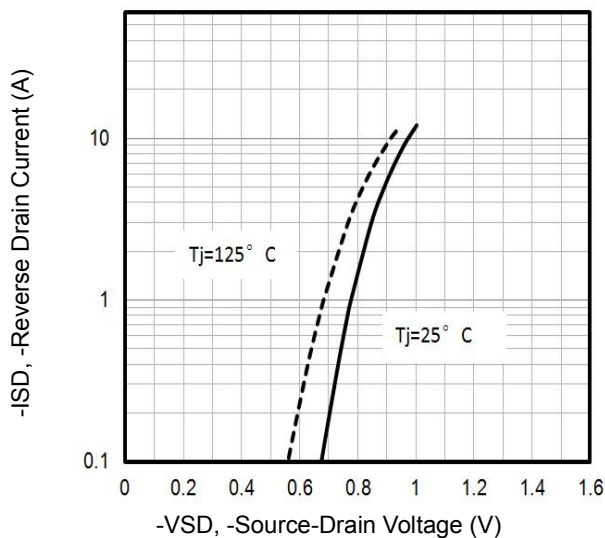


Fig5. Typical Source-Drain Diode Forward Voltage

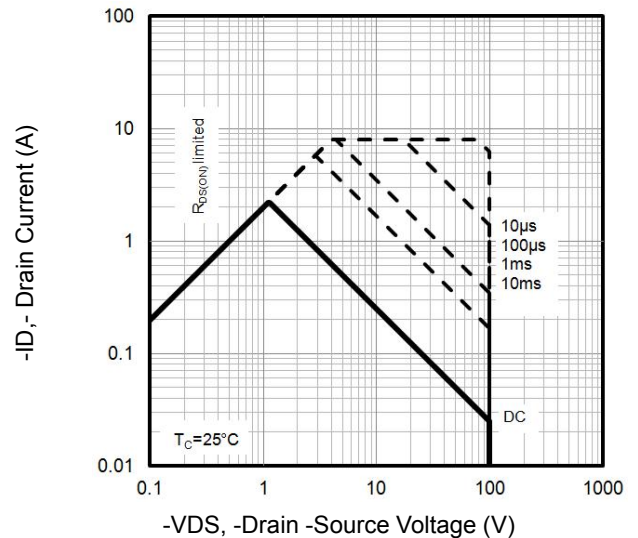


Fig6. Maximum Safe Operating Area



Typical Characteristics

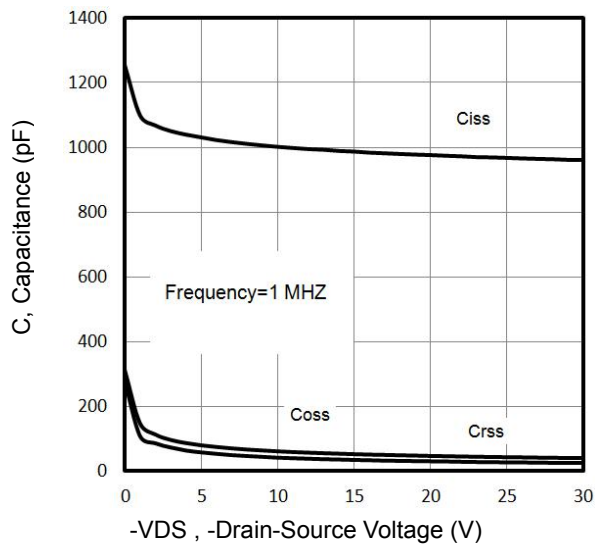


Fig7. Typical Capacitance Vs. Drain-Source Voltage

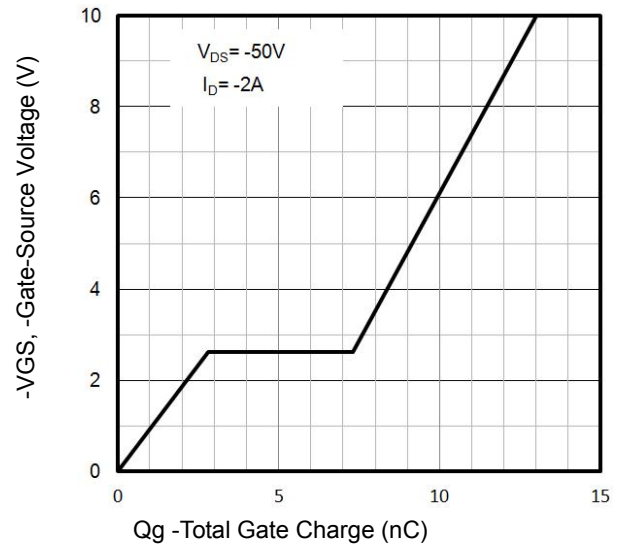


Fig8. Typical Gate Charge Vs. Gate-Source Voltage

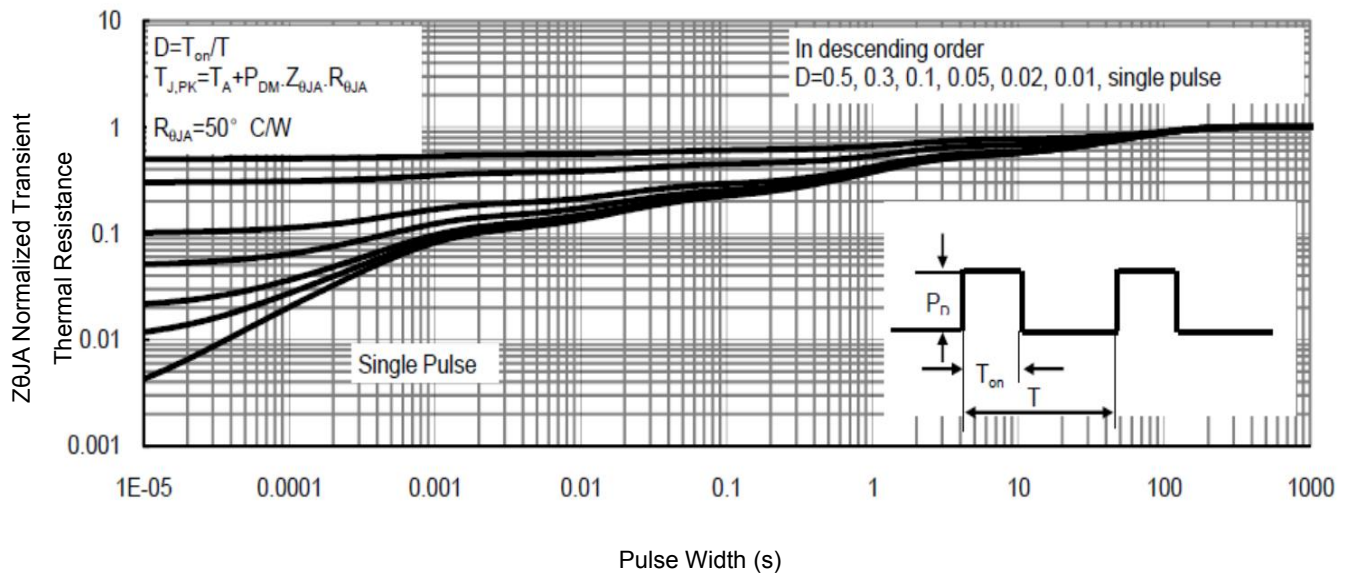


Fig9. Normalized Maximum Transient Thermal Impedance

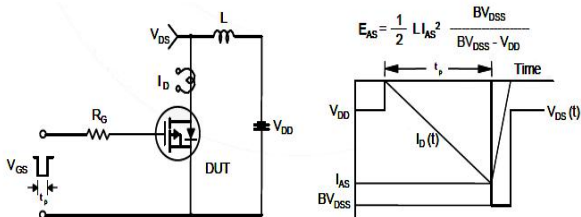


Fig10. Unclamped Inductive Test Circuit and Waveforms

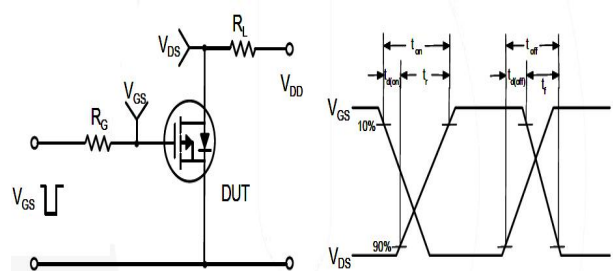
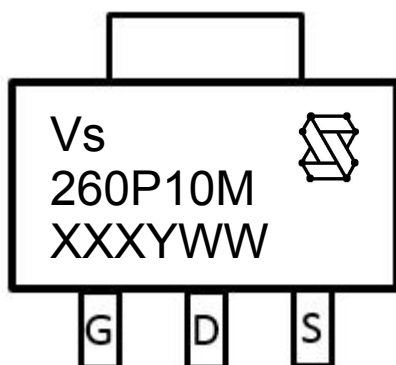


Fig11. Switching Time Test Circuit and waveforms



Marking Information



1st line: Vanguard Code (Vs), Vanguard Logo

2nd line: Part Number (260P10M)

3rd line: Date code (XXXYWW)

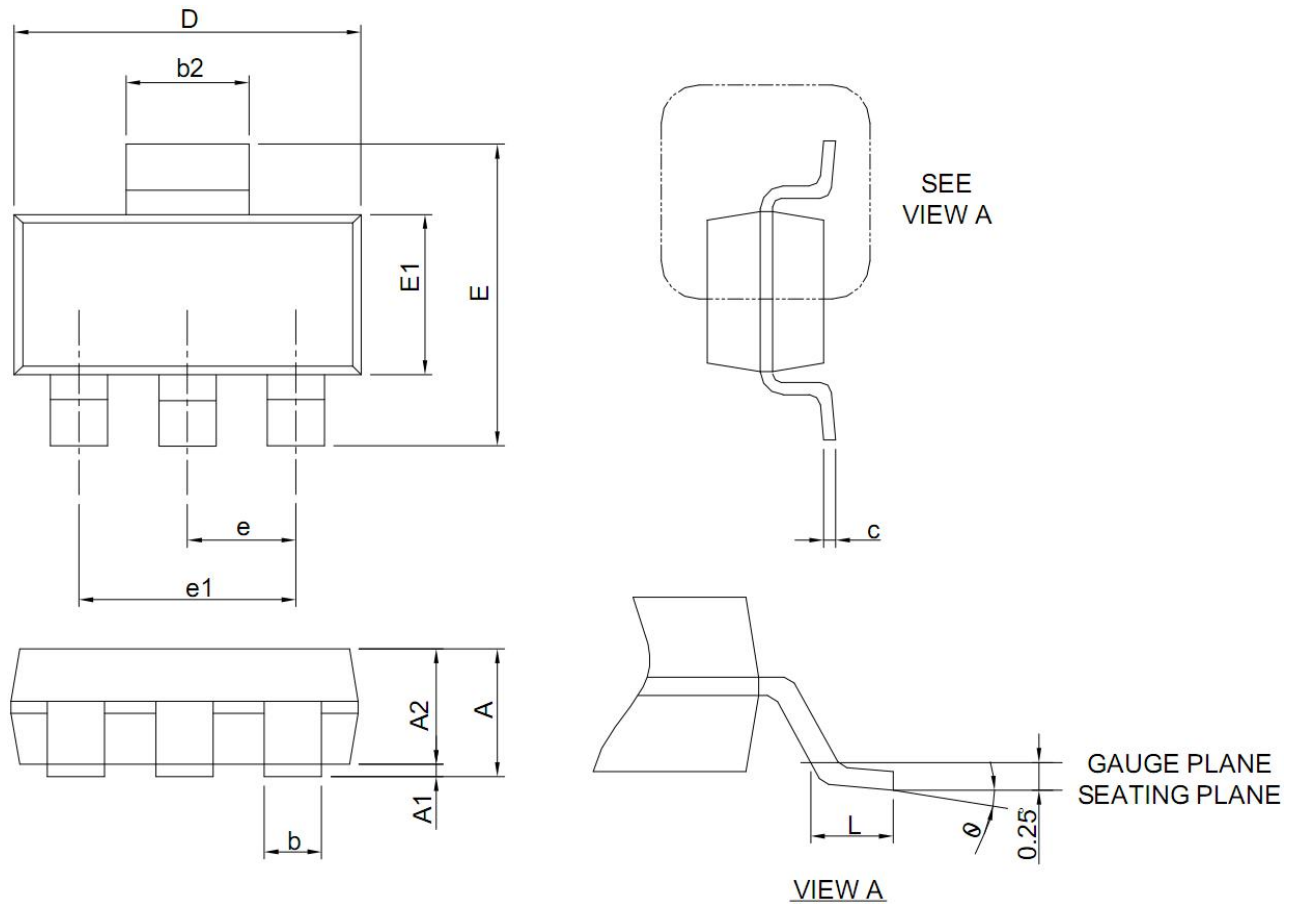
XXX: Wafer Lot Number Code , code changed with Lot Number

Y: Year Code, (e.g. E=2017, F=2018, G=2019, H=2020, etc)

WW: Week Code (01 to 53)



SOT223 Package Outline Data



Symbol	Dimensions (unit: mm)		
	Min	Typ	Max
A	1.50	1.65	1.80
A1	0.02	0.06	0.10
A2	1.50	1.60	1.70
b	0.66	0.72	0.80
b2	2.90	3.00	3.10
c	0.23	0.30	0.35
D	6.30	6.50	6.70
E	6.70	7.00	7.30
E1	3.30	3.50	3.70
e	2.30 REF		
e1	4.60 REF		
L	0.75	--	1.15
θ	0 °	--	10 °

Notes:

1. Refer to JEDEC TO-261 variation AA
2. Dimensions "D" and "E1" do NOT include mold flash, tie bar burrs, gate burrs and interlead flash.

Customer Service

Sales and Service:

sales@vgsemi.com

Vanguard Semiconductor CO., LTD

TEL: (86-755) -26902410

FAX: (86-755) -26907027

WEB: www.vgsemi.com